

SPECIFICATIONS FOR MODULE

CUSTOMER	廣達
MODEL	WD-FD070V-NFLWf VER. 5
CUSTOMER APPROVED	

APPROVED BY	CHECKED BY	ORGANIZED BY
LCM 產品部	LCM 產品部	LCM 產品部
2012/6/26	2012/6/26	2012/6/26
黃建民	陳彥勳	李範

APPROVAL FOR SPECIFICATIONS ONLY

APPROVAL FOR SPECIFICATIONS AND SAMPLE 112020540-1.1

No.10, Jianguo Rd., Tanzi Dist., Taichung City 42760, Taiwan (R.O.C.)

TEL:886- 4-25318899, FAX: 886- 4-25310868



History of Version

Version	Contents	Date	Note
a1	New Version	2011.Mar.14	SPEC
a2	Change by Customer Change IC: HX8520A ITE IT7260	2011.Mar.24	SPEC
a3	Change by Customer 4.1 LCM Mechanical Diagram	2011.Mar.28	SPEC
a4	Change by Customer 4.1 LCM Mechanical Diagram	2011.Mar.30	SPEC
a5	Change by Customer 4.1 LCM Mechanical Diagram	2011.Apr.07	SPEC
а6	Change by Customer 4.1 LCM Mechanical Diagram	2011.Apr.11	SPEC
a7	Change by Customer Customer: QCI 4.1 LCM Mechanical Diagram	2011.Jun.02	SPEC
а8	Change by Customer 3.1 LCM Electro-optical Characteristics Luminance 4.1 LCM Mechanical Diagram 4.2 Packing Method 5.1-6. Inspection specification 5.2 Standard Specification for Reliability 6.1 Product Substances Management Documentation	2011.Jun.14	SPEC
a9	Change by Customer 4.1 LCM Mechanical Diagram 6.1 Product Substances Management Documentation	2011/7/11	SPEC
b1	Change by Customer 4.1 LCM Mechanical Diagram	2011/7/11	SPEC
b2	Change by Customer 4.1 LCM Mechanical Diagram 5.1-6. Inspection specification	2011/7/29	SPEC
b3	Change by Customer 4.1 LCM Mechanical Diagram	2011/8/10	SPEC
b4	Change by Customer 4.1 LCM Mechanical Diagram 4.2 Packing Method	2011/9/2	Sample
f1	Change by Customer Without AS coating	2012/02/15	SPEC
f2	Change by Customer 4.1 LCM Mechanical Diagram	2012/02/21	SPEC
f3	For sample	2012/03/27	Sample
f4	Modify 1.6 LCM BAR CODE INFORMATION	2012/4/10	Sample
f5	Change by Customer Add 4.2 CMI LCM BAR CODE INFORMATION 4.3 WINTEK PRINT DATECODE INFORMATION	2012/6/26	Sample



Contents

Absolute Maximum Ratings(1) LCM	4
1.1 Electrical Characteristics	
1.2 Interface Pin Function	
1.3 Timing Characteristic	
1.4 Power ON/OFF SEQUENCE	
(2) FIP(Field Induced Pad)	
2.1 FIP Electrical Characteristics	
2.2 FIP Interface Pin Function	
2.3 FIP Interface Diagram	
2.4 FIP Schematic	
2.5 FIP Timing Characteristic	
2.6 FIP Protocol	14
(3) Electro-optical Unitss	15
3.1 LCM Electro-optical Characteristics	15
3.2 Optical Definitions	19
(4) LCM Mechanical Units	20
4.1 LCM Mechanical Diagram	20
4.2 CMI LCM BAR CODE INFORMATION	21
4.3 WINTEK PRINT DATECODE INFORMATION	21
4.4 Packing Method	22
(5) Quality Units	
5.1 Specification of Quality Assurance	23
5.2 Standard Specification for Reliability	36
5.3 Precautions in Use of LCM	
(6) Substance Management Units	
6 1 Product Substances Management Documentation	



Absolute Maximum Ratings

ITEM	SYMBOL	MIN	TYP	MAX	UNIT	
Operating Temperature	TOP	-20	-	+60		
Storage Temperature	TST	-30	-	+70		
Supply Voltage for Analog	VCI-VSS	-0.3	-	5.0	V	
Supply Voltage for Digital	VDD-VSS	6.5	-	13.5	V	
Static Electricity	Be sure that you are grounded when handing LCM.					

(1) LCM

1.1 Electrical Characteristics

(Ta=25

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Supply Voltage for Analog	VCI	-	10.8	11	11.2	V
Supply Voltage for Digital	VDD	-	3.0	3.3	3.6	V
Input Signal High Voltage	VIH	-	0.7VDD	-	VDD	V
Input Signal Low Voltage	VIL	-	0	-	0.3VDD	V
Output Signal High Voltage	VOH		-	-	-	V
Output Signal Low Voltage	VOL			ı	-	V
Supply Current for Analog	*ICI	VCI=11V	-	25	30	mA
Supply Current for Digital	*IDD	VDD=3.3V	-	50	60	mA
Used IC						,

^{*}ICI Measurement condition is for all pixels on

^{*}IDD Measurement condition is for all pixels on



1.2 Interface Pin Function

CN1:

SYMBOL	1/0	FUNCTION
VCOM	Р	Common Voltage
VDD	Р	Power Voltage for digital circuit
VDD	Р	Power Voltage for digital circuit
NC	-	No connection
Reset		Global reset pin
STBYB	1	Standby mode, Normally pulled high STBYB = "1", normal operation STBYB = "0", timing controller, source driver will turn off, all output are High-Z
GND	Р	Ground
RXIN0-		- LVDS differential data input
RXIN0+		+ LVDS differential data input
GND	Р	Ground
RXIN1-		- LVDS differential data input
RXIN1+		+ LVDS differential data input
GND	Р	Ground
RXIN2-	l	- LVDS differential data input
RXIN2+		+ LVDS differential data input
GND	Р	Ground
RXCLKIN-		- LVDS differential data input
RXCLKIN+	1	+ LVDS differential data input
GND	Р	Ground
RXIN3-	И	- LVDS differential data input
RXIN3+		+ LVDS differential data input
GND	Р	Ground
NC	-	No connection
NC	-	No connection
GND	Р	Ground
NC	-	No connection
DIMO	0	Backlight CABC controller signal output
SELB		6bit/8bit mode select
AVDD	Р	Power for Analog Circuit
GND	Р	Ground
LED-	Р	LED Cathode
LED-	Р	LED Cathode
L/R		Horizontal inversion
U/D		Vertical inversion
VGL	Р	Gate OFF Voltage
	VCOM VDD VDD VDD NC Reset STBYB GND RXIN0- RXIN0- RXIN1- RXIN1+ GND RXIN2- RXIN2+ GND RXIN2- RXIN3+ GND RXIN3- RXIN3+ GND RXIN3- RXIN3	VCOM P VDD P VDD P NC - Reset I STBYB I GND P RXIN0- I RXIN0- I RXIN0- I RXIN1- I RXIN1- I RXIN2- I RXIN3- I RXCLKIN- I RXIN3- I RXIN4- I GND P NC - O SELB I



36	CABCEN1	l	CABC H/W enable
37	CABCEN0	l	CABC H/W enable
38	VGH	Р	Gate ON Voltage
39	LED+	Р	LED Anode
40	LED+	Р	LED Anode



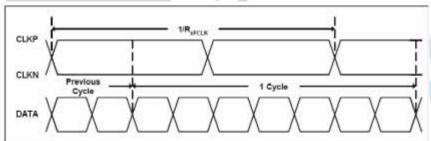


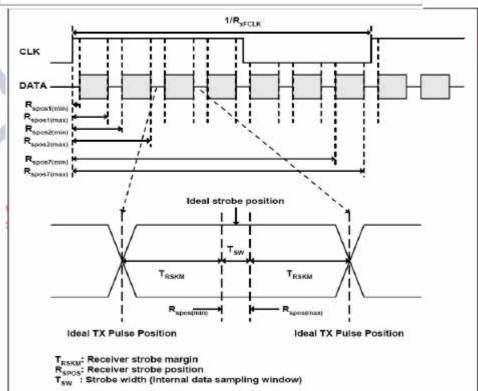
1.3 Timing Characteristic

1.3.1. AC Electrical Characteristics

Parameter	Cumbal		Limit	Damanic		
	Symbol	Min.	Тур.	Max.	Unit	Remark
Clock frequency	R _{xFCLK}	40.8	51.2	71	MHz	
Input data skew margin	T _{RSKM}	500	¥.	0-0	ps	10 /
Clock high time	T _{LVCH}		4/(7* R _{xFCLK})	-	ns	-
Clock low time	T _{LVCL}		3/(7* R _{xFCLK})	(2)	ns	

1.3.2. Input Clock and Data Timing Diagram

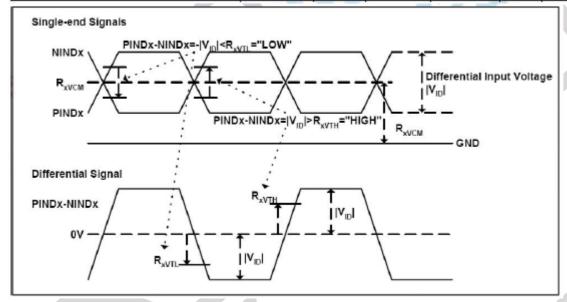






1.3.3. DC Electrical Characteristics

Parameter	Symbol		Value	Unit	Remark	
Tarameter		Min.	Typ.	Max.	Onic	Itemark
Differential input high Threshold voltage	R _{xVTH}	5	ie.	+0.1	V	R _{XVCM} =1.2V
Differential input low Threshold voltage	R _{xVTH}	-0.1	2	4-7	V	TXVCM-1.2V
Input voltage range (singled-end)	R _{xVIN}	0	-1	2.4	٧	
Differential input common mode voltage	R _{xVCM}	V _{ID} /2	11/6	2.4- V _{ID} /2	V	
Differential voltage	[V _{ID}]	0.2	10	0.6	V	
Differential input leakage current	RV _{xliz}	-10	P .	+10	uA	
	30000	0				



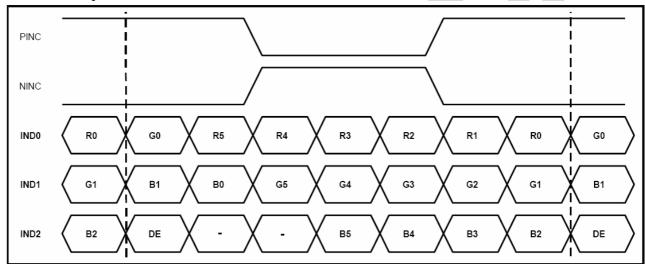
1.3.4. Timing

Item	Cumubal		Values	Unit	Remark	
item	Symbol	Min.	Тур.	Max.	Unit	Remark
Clock Frequency	fclk	40.8	51.2	67.2	MHz	Frame rate =60Hz
Horizontal display area	thd		1024	2000	DCLK	100
HS period time	th	1114	1344	1400	DCLK	
HS Blanking	thb	90	320	376	DCLK	
Vertical display area	tvd	-	600	2	Н	
VS period time	tv	610	635	800	Н	
VS Blanking	thb	10	35	200	Н	

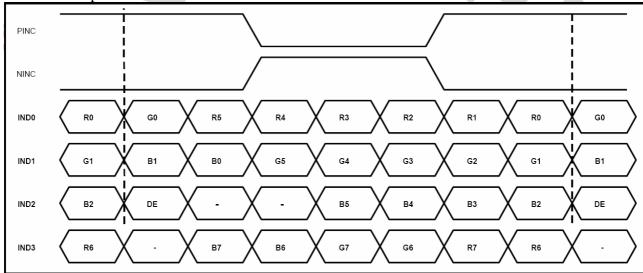


1.3.5. Data Input Format

6bit LVDS input



8bit LVDS input

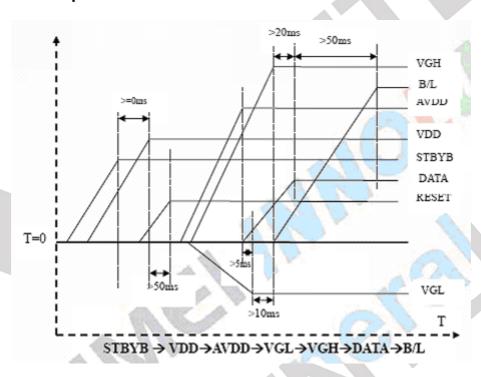


Note: Support DE timing mode only, SYNC mode not supported.

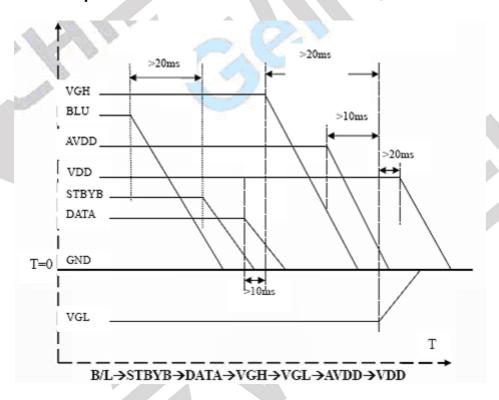


1.4 Power ON/OFF SEQUENCE

1.4-1 Power ON Sequence



1.4-2 Power OFF Sequence





(2) FIP(Field Induced Pad)

2.1 FIP Electrical Characteristics

(Ta=25

							•	,
ITEM		SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	Remark
Input Power Voltage		V_{DD_TP}	-	3.2	3.3	3.4	V	ı
Input Signal Voltage	H Level	V_{IH}	-	$0.7V_{DDTP}$	ı	_	V	
input digital voltage	L Level	V_{IL}		-	I	0.3V _{DDTP}	V	1
Output Signal Voltage	H Level	V _{OH}	loh=2mA	2.4	1	_	V	
Output Signal Voltage	L Level	V_{OL}	Iol=2mA	0	ı	0.4	V	_
Report Rate			One-finger	ı	130	-	Hz	ı
Interface			-		12	С		
Touch Panel Resolution			-		1024	x768		-
Supply Current		*IDD	V_{DD_TP} =3.3v	-		TBD	mA	ı
Input Finger						-		
Driver IC		ITE IT7260					-	

2.2 FIP Interface Pin Function

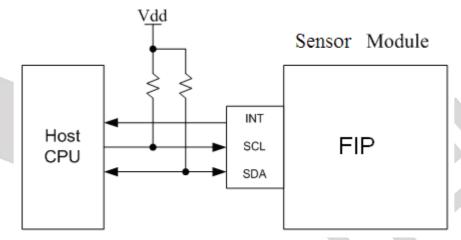
NO	SYMBOL	I/O	FUNCTION
1	VDDTP	Р	Supply Voltage
2	INT	1	Interrupt pin
3	SCL	I/O	I2C SCL pin
4	SDA	I	I2C SDA pin
5	GND	Р	Ground
6	NC	ı	NC pin



2.3 FIP Interface Diagram

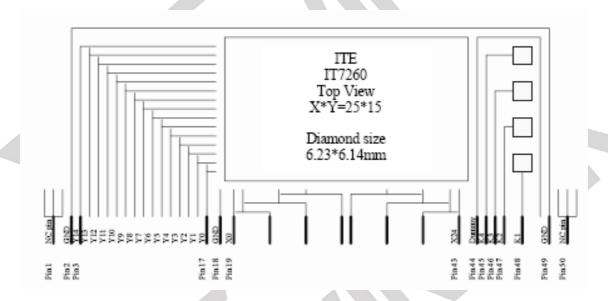
The system block diagram is as shown in below. There are three communication pins connected between CPU and Sensor Module, which are including external interrupt INT, I2C pins SCL and SDA. The INT is active low while the touch state is calculated by Sensor Module and the touch information can be translated via I2C communication interface. The I2C data format, protocol and report packet are described as following.

System block diagram



2.4 FIP Schematic

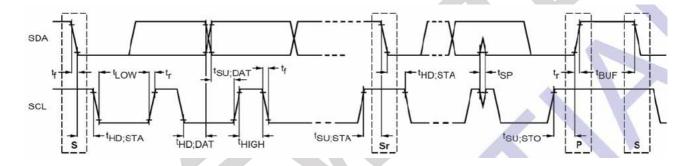
Sensor trace:





2.5 FIP Timing Characteristic

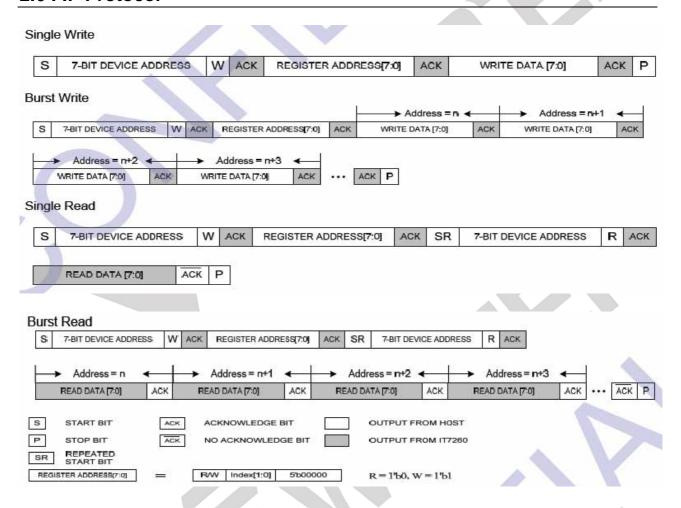
I2C interface



Symbol	Parameter	Min.	Max.	Unit
f _{SCL}	SCL clock frequency	1	400	kHz
	Hold time (repeated) START condition		_	us
t _{HD;STA}	After this period, the first clock pulse is generated.			
t _{LOW}	LOW period of the SCL clock	1.3	-	us
t _{HIGH}	HIGH period of the SCL clock	0.6	-	us
t _{su;sta}	Set-up time for a repeated START condition	0.6	-	us
t _{HD;DAT}	Data hold time	0	0.9	us
t _{SU;DAT}	Data setup time	100	-	ns
t _r	Rise time of both SDA and SCL signals	20+0.1C _b	300	ns
t _f	Fall time of both SDA and SCL signals	20+0.1C _b	300	ns
t _{su;sto}	Set-up time for STOP condition	0.6	-	us
t _{BUF}	Bus free time between a STOP and START condition	1.3	-	us
Сь	Capacitive load for each bus line	-	400	pF
V _{nL}	Noise margin at the LOW level for each connected device (including hysteresis)	$0.1V_{DD}$	-	V
V _{nH}	Noise margin at the HIGH level for each connected device (including hysteresis)	0.2V _{DD}	-	V
t _{timeout}	Cumulative SCL low timeout limit	3	5	ms



2.6 FIP Protocol





(3) Electro-optical Unitss

3.1 LCM Electro-optical Characteristics

17714	0)/1	1001	COMPITION	24121	TVD	BAAN	
ITEM	SYN	IBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
	ψ= 90	° (12H)			70	-	deg.
View Angle	ψ= 270 ° (6H)		CR>=10		75	1	deg.
(Transmissive)	ψ= 180	0 ° (9H)	0112-10		75	-	deg.
	ψ= 0	° (3H)			75	1	deg.
Contrast Ratio (Transmissive)	C	R	Ta=25	500	700	-	-
Response Time	Tr	+Td	Ta=25	-	10	20	ms
Luminance		L	Normal = =0°	280	350	-	cd/m2
	Red	Rx		-	TBD	-	
	Reu	Ry	Normal	-	TBD	-	
	Croon	Gx		-	TBD	-	
Color Coordinate	Green	Gy		-	TBD	-	
	Blue	Bx	= =0)	TBD	-	-
	Diue	Ву	Ta=25	-	TBD	-	
	White	Wx		0.26	0.31	0.36	
	VVIIIC	Wy		0.28	0.33	0.38	
LCD Type			TFT , (POSIT	IVE / Trar	nsmissive)	•
Gray Inversion Direction	1	-		6:00		-	



Note 1: Definition of viewing angle range

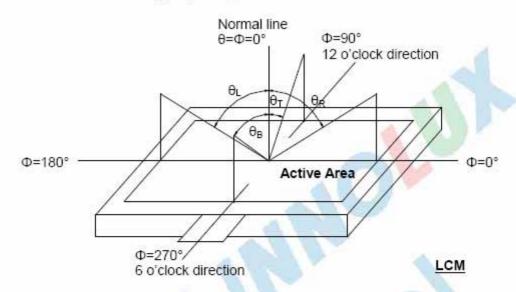


Fig. 4-1 Definition of viewing angle

Note 2: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 30 minutes operation, the optical properties are measured at the center point of the LCD screen. (Response time is measured by Photo detector TOPCON BM-7, other items are measured by BM-5A/Field of view: 1° /Height: 500mm.)

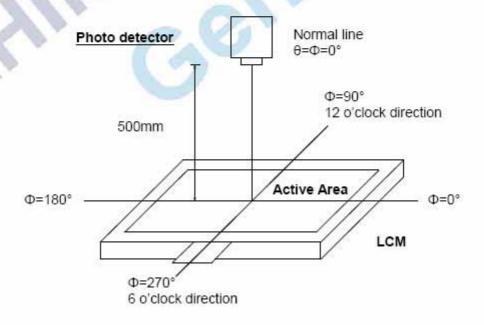


Fig. 4-2 Optical measurement system setup



Note 3: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.

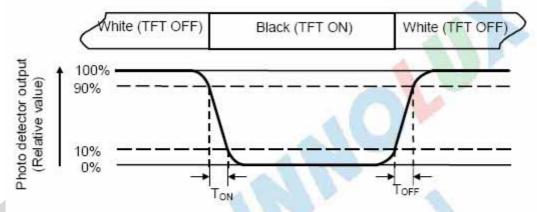


Fig. 4-3 Definition of response time

Note 4: Definition of contrast ratio

Contrast ratio (CR) = Luminance measured when LCD on the "White" state

Luminance measured when LCD on the "Black" state

Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

Note 6: All input terminals LCD panel must be ground while measuring the center area of the panel. The LED driving condition is I_L=120mA.



Note 7: Definition of Luminance Uniformity
Active area is divided into 9 measuring areas (Refer to Fig. 4-4). Every measuring point is placed at the center of each measuring area.

asuring point is placed at the center of e
$$Luminance \ Uniformity \ (Yu) = \frac{B_{min}}{B_{max}}$$

L-----Active area length -- Active area width

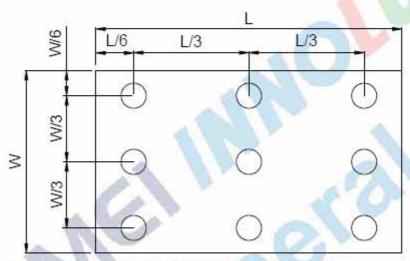
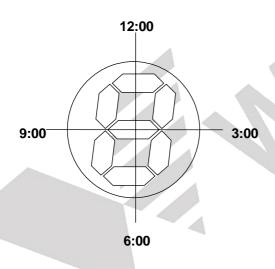


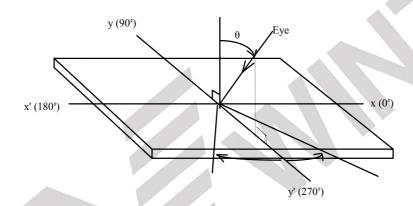
Fig. 4-4 Definition of measuring points

 \mathbf{B}_{max} : The measured maximum luminance of all measurement position. \mathbf{B}_{min} : The measured minimum luminance of all measurement position.



3.2 Optical Definitions





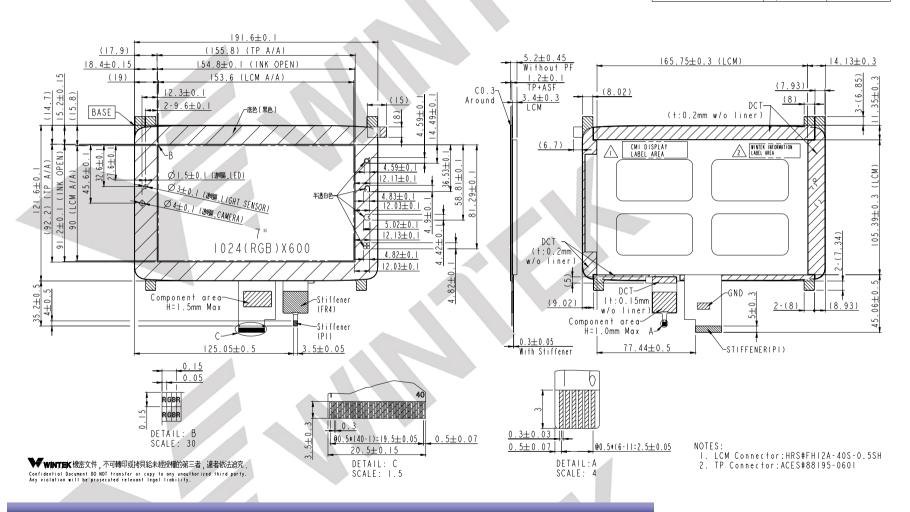
View Angle



(4) LCM Mechanical Units

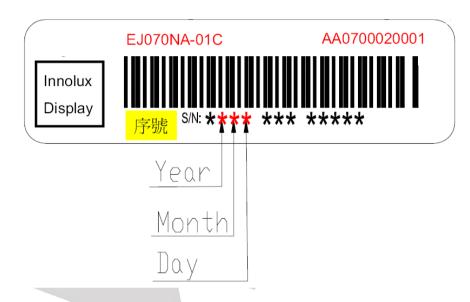
4.1 LCM Mechanical Diagram

TOLERANCES NOT SPECIFIED: .X=±	0.3	.XX=±0.	30 .	X° =± 2°	. X X° =±0.5°
(XXX.XX):REFERENCE DIMENSION	-	+	(3)	UNI	T : mm





4.2 CMI LCM BAR CODE INFORMATION



4.3 WINTEK PRINT DATECODE INFORMATION

WD-FD070V-NFLWf model xx/xx week/year Xxxxxxxxxxxx LOT No:



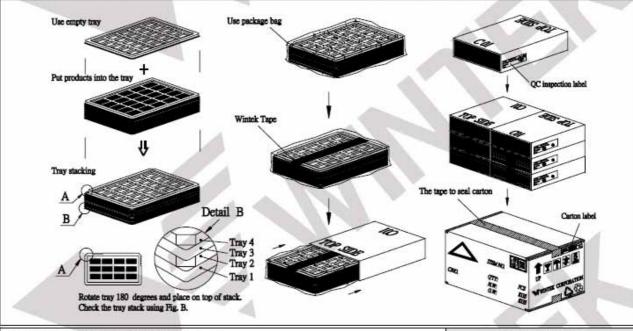
4.4 Packing Method

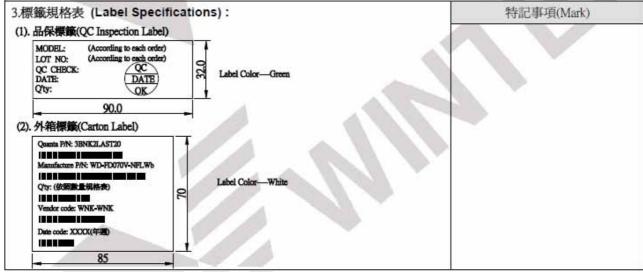
Item	Mo	del	Dimensions(mm)	Unit Weight(kg)	Quantity
成品 (Product)	LC	M	191.6*121.6	0.22	60
Tray 盤 (Tray)	VR45	PET	320*217*16*1.0	0.1	36
包裝袋 (Package Bag)	0	5	467*321*0.08	0.023	6
內紙盒 (Product Box)	0	01	320*219*70	0.131	6
外紙箱 (Carton)	C	62	475*345*250	0.857	1
Label			85*70	0.002	1
總重量 (Total Weight)			18.5 Kg ± 5 %		

2.包裝數量規格表 (Packaging Specifications and Quantity):

(1) LCM quantity per tray : no. per row $2 \times no.$ per column 1 = 2 (2) LCM quantity per box : quantity per tray $2 \times no.$ of trays 5 = 10

(3) Total LCM quantity in carton: quantity per box 10 x no. of boxes 6 = 60







(5) Quality Units

5.1 Specification of Quality Assurance

5.1-1.Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by WINTEK CORPORATION (Supplier).

5.1-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to ANSI/ASQC Z1.4-2003.General Inspection Level take a single time.
- (ii) The defects classify of AQL as following:

Major defect: AQL=0.65
Minor defect: AQL=2.5
Total defects: AQL=2.5

5.1-3. Nonconforming Analysis & Deal With Manners

- a. Nonconforming analysis:
 - (i) Purchaser should supply the detail data of non-conforming sample and the non-suitable state.
 - (ii) After accepting the detail data from purchaser, the analysis of nonconforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before two weeks.
- b. Disposition of nonconforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
- (ii) Both supplier and customer should analyze the reason and discuss the disposition of nonconforming when the reason of nonconforming is not sure.



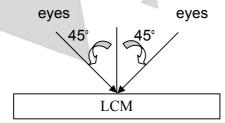
5.1-4. Agreement items

Both sides should discuss together when the following problems happen.

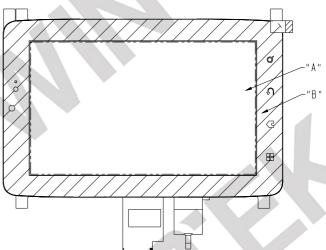
- a. There is any problem of standard of quality assurance, and both sides think that it must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

5.1-5. Standard of The Product Appearance Test

- a. Manner of appearance test:
 - (i) The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30 cm.
 - (ii) When display on use front-light test, while display off use back-light test.
 - (iii)The test direction is base on about around 45° of vertical line.



(iv) Definition of area:



A Area: Viewing area.

B Area: Out of viewing area (Outside viewing area)

Any defect at area B could be ignored. If customer has particular requirement, this requirement should be clearly defined in inspection specification. If inspection specification has defined other criteria, the final judgement should follow the inspection specification.

- b. Basic principle:
 - (i) It will accord to the AQL when the standard can not be described.
 - (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
 - (iii) Must add new item on time when it is necessary.



5.1-6. Inspection specification

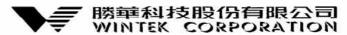


Wintek Display TFT Module	Inspection Criteria	NO. M1L070012 Inspection Criteria
REVISION DATE: 2010/10/19	Version: V5.0	PAGE: 1 OF 10

Wintek Display TFT Module Inspection Criteria

NOTE - All of the modification on inspection criteria are needed to record by proposer with signing.





Wintek Display TFT Module Inspection Criteria		NO. M1L070012 Inspection Criteria	
REVISION DATE: 2010/10/19	Version: V5.0	PAGE: 2 OF 10	

Change History:

ISSUE	DATE	ORIGINATOR	DETAILS OF CHANGE	PAGE
V1.0	2007,09,18	Alvin Wang	New Version	1~9
V2.0	2007,10,04	Alvin Wang	Update Sec 02_LCM black, white spot, Inner dirt, bright and color dot.	3,4
V3.0	2008,06,17	Shyn-Jeng Chen	Update Sec 02_LCM black, white spot, Inner dirt, bright and color dot	
		- A	Item 2.1.1: Modify table and regarding	3
		00	Item 2.1.2: Modify table and regarding	3
	204		Item 2.2.1: Modify table and regarding	4
			Item 2.2.2: Modify table and regarding	4
			Item 2.3.1: Modify table and regarding	4
			Item 2.3.2: Modify table and regarding	4
		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Update Sec 03_LCM Naked line, black& white line.	
			Item 3.1.1: Modify table and regarding	
			Item 3.1.2: Modify table and regarding	5
			Item 3.2.1: Modify table and regarding	5
			Item 3.2.2: Modify table and regarding	5
			Item 3.3.1: Modify table and regarding	5
			Item 3.3.2: Modify table and regarding	6
			Update Sec 04_LCM Dot defect.	6
		- 4	Item 4.1: Modify Dot defect inspection criteria;	
			Update Sec 05_LCM Polarizer.	6
			Item 5.1: Modify Polarizer Bubble, dent, concave	
			&convex dot inspection criteria;	7
V4.0	2009,12,11	Shyn-Jeng Chen	Update Sec 03 LCM Naked line, black& white line.	2
	51 0		Item 3.1.1: Modify the LCM from CSTN to TFT.	5
			Item 3.2.1: Modify the LCM from CSTN to TFT.	5
- 4			Item 3.3.1: Modify the LCM from CSTN to TFT.	6
V5.0	2010,10,19	Shyn-Jeng Chen	Update Sec 02_ LCM Black white spot, Inner dirt, bright and color dot	5_
			Item 2.4 : Add 8" ≤ Sample Size inspection criteria.	
			Reason: To Standard 8" ≤ Sample Size inspection	
			criteria.	
			Update Sec 03 Naked line, Black white line	7
				X.);
			Item 3.4 : Add 8" ≤ Sample Size inspection criteria.	
			Reason: To Standard 8" ≤ Sample Size inspection	
			criteria.	





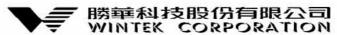
Wintek Display TFT Module	Inspection Criteria	NO. M1L070012 Inspection Criteria
REVISION DATE: 2010/10/19	Version: V5.0	PAGE: 3 OF 10

No	Item		Criter	ion		AQL
01	General test	 1.1 Missing vertical or horizontal line, shallow vertical or horizontal line. 1.2 Missing character (including missing dot or excess dot), missing icon. 1.3 Display malfunction. 1.4 Stripe of same width or slanting stripe defect. (Tolerance: ±45°) 1.5 No function or no display. 1.6 Current consumption, chromaticity and brightness exceed in product Specification. (The above Current consumption specified max. value) 1.7 Picture scanning program must be complete and continuous. 1.8 LCD viewing angle defect/error. 1.9 Mixed product types or versions. 1.10 For Touch Panel product test, T/P function must be normal. 				
4			LCD Size < 3" Size	inspection cr	iteria	
02	LCM black, White spot, Inner dirt, bright and color dot	φ = (x + y)/2 X ↓ Y So Ignore non-view Regarding 0.1m dense, gap distance	Size $ \psi \leq 0.1 \text{mm} $ $0.1 \text{mm} < \psi \leq 0.25 \text{mm} $ $0.25 \text{mm} < \psi \leq 0.35 \text{mm} $ $ \psi > 0.35 \text{mm} $ $ \psi \text{ving area.} $ $ \text{ving 4} $ $ \text{ving 4} $	Acceptable Q'TY Ignore Ignore 2 0 otable Q'TY c	Minimum separated distance Ignore (Accept dense) Ignore (Accept no dense) 5mm ould ignore and accept no	Mino Defec
			Size	Acceptable Q'TY	Minimum separated distance	
			ψ≤ 0.1mm	Ignore	Ignore (Accept dense)	
			0.1<ψ≤0.25mm	Ignore	Ignore (Accept no dense)	
			0.25mm<ψ≦0.35mm	4	5mm	
			ψ>0.35mm	0		
			m< φ ≦0.25mm, Accep	otable Q'TY c	ould ignore and accept no	



Minor

Defect



NO. M1L070012 Wintek Display TFT Module Inspection Criteria Inspection Criteria REVISION DATE: 2010/10/19 Version: V5.0 PAGE: 4 OF 10

3"≤LCD Size < 5" Size inspection criteria

2.2 Spot type: (as following fig)

2.2.1 Applicable to LCM TFT, not including Touch Panel.

φ=	(x + y)	/ 2
 ⊳	^X ←	Ţ
		$\dot{}_{Y}$
		T

Size	Acceptable Q'TY	Minimum separated distance
ψ≦0.1mm	Ignore	Ignore (Accept dense)
0.1mm<ψ≦0.25mm	Ignore	Ignore (Accept no dense)
0.25mm<ψ≦0.4mm	40	10mm
ψ>0.4mm	0	1 - 20 - 20 - 20 - 20 - 20 - 20 - 20 - 2

- Ignore non-viewing area.
- \odot Regarding 0.1mm $< \phi \le$ 0.25mm, Acceptable Q'TY could ignore and accept no dense, gap distance is 1mm.
- 2.2.2 Judgment specification including Touch Panel as follow.

Size	Acceptable Q'TY	Minimum separated distance
ψ≦0.1mm	Ignore	Ignore (Accept dense)
0.1mm<ψ≦0.25mm	Ignore	Ignore (Accept no dense)
0.25mm<ψ≦0.45mm	5	10mm
ψ>0.45mm	0	-

White spot, Inner dirt, bright and color dot

02

- LCM black, ⊚ Ignore non-viewing area.
 - **②** Regarding 0.1mm $< \phi \le$ 0.25mm, Acceptable Q'TY could ignore and accept no dense, gap distance is 1mm.

5"≤ LCD Size < 8" Size inspection criteria

- 2.3 Spot type : (as following fig)
- 2.3.1 Applicable to LCM TFT, not including Touch Panel.

Ψ-(x + y	
→	` ⊭−	- 🗼
		Ż
		1

1	Size	Acceptable Q'TY	Minimum separated distance
	γ ≦0.1mm	Ignore	Ignore (Accept dense)
1	0.1mm<ψ≤0.25mm	Ignore	Ignore (Accept no dense)
	0.25mm<ψ≦0.45mm	5	10mm
	ψ>0.45mm	0	/-

- Ignore non-viewing area.
- dense, gap distance is 1mm.
- 2.3.2 Judgment specification including Touch Panel as follow.

Size	Acceptable Q'TY	Minimum separated distance
y≤0.1mm	Ignore	Ignore (Accept dense)
0.1mm<ψ≦0.25mm	Ignore	Ignore (Accept no dense)
0.25mm<ψ≤0.5mm	6	10mm
ψ>0.5mm	0	220

Olgnore non-viewing area.

⊙ Regarding 0.1mm $< \phi \le$ 0.25mm, Acceptable Q'TY could ignore and accept no dense, gap distance is 1mm.

WD-FD070V-NFLWf VER.05

28/59





Wintek Display TFT Module Inspection Criteria

REVISION DATE: 2010/10/19

Version: V5.0

NO. M1L070012
Inspection Criteria
PAGE: 5 OF 10

	Ĭ	96			AN ADMINISTRAÇÃO SE			
		8"≤ LCD Size Size inspection criteria						
		2.4 Spot type : (as following fig)						
		2.4.1 Applicable to LCM TFT, not including Touch Panel.						
		$\phi = (x + y)/2$ X	Size	-	Acceptable Q'TY	Mi	nimum separated distance	
		→ _	ψ≦0.1mm	1	Ignore	Ign	ore (Accept dense)]
		- Y	$0.1 \text{mm} < \psi \leq 0.25$	COMPANY.	Ignore	Ignor	e (Accept no dense)]]
			0.25mm<ψ≤0.45m	mm	5		10mm]
	DOS AND		ψ>0.45mm		0		==	4
02	LCM black, White spot, Inner dirt, bright and	 Ignore non-view Regarding 0.1mg dense, gap distance 2.4.2 Judgment specific 	m < φ ≤0.25mm, A e is 1mm.			NI ANN	1	O Minor Defect
	color dot	2.4.2 Guagment sp	7	19 10	Acceptable	-	nimum separated	
4			Size		Q'TY		distance	
		\ \	ψ ≤ 0.1mm	1	Ignore	Igne	ore (Accept dense)	
			$0.1 \text{mm} < \psi \le 0.25 \text{m}$		Ignore	Ignor	e (Accept no dense)	P.
			0.25mm<ψ≤0.5n	nm	6		10mm	
			ψ>0.5mm		0		-	1
			and the second s	ccep	table Q'TY co	ould ig	nore and accept n	0
03	Naked		LCD Size < 3"	Size i	nspection cr	iteria		Minor
	line, black& white	3.1 Line type : (as 3.1.1 Applicable to		uding	Touch Panel			Defect
	line	1	Length (L)		Width (W)		Acceptable Q'TY	
		~ ↓ W	Ignore		W≤0.03i	nm	Ignore	all .
		→ L 🚛	L≤8.0mm	0.03	mm <w≦0.0< td=""><td>5mm</td><td>4</td><td>**</td></w≦0.0<>	5mm	4	**
			L≤5.0mm		5mm <w≦0.< td=""><td></td><td>2</td><td></td></w≦0.<>		2	
- 4			9 4	ā	1mm <w< td=""><td></td><td>0</td><td></td></w<>		0	
			-	0.	IIIIIII 🔍 V V			-
		3.1.2 Touch Panel j	udgment specifica	tion a	as follow.	_		
			Length (L)		Width (W)		Acceptable Q'TY	F.
			Ignore		W≦0.03mm		Ignore	
			L≦12.0mm	0.03	mm <w≦0.0< td=""><td>5mm</td><td>5</td><td></td></w≦0.0<>	5mm	5	
			L≦6.0mm	0.0	5mm <w≦0.1< td=""><td>mm</td><td>3</td><td></td></w≦0.1<>	mm	3	
			4		0.1mm <w< td=""><td></td><td>0</td><td>1</td></w<>		0	1
		Note: Applicable to o Ignore non-view o Judge as OK sar	ing area	visibl	e in square v	iewing	angle.	





Wintek Display TFT Module Inspection Criteria

REVISION DATE: 2010/10/19

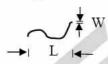
Version: V5.0

NO. M1L070012
Inspection Criteria
PAGE: 6 OF 10

3"≤ LCD Size < 5" Size inspection criteria

3.2 Line type: (as following fig)

3.2.1 Applicable to LCM TFT, not including Touch Panel.



Length (L)	Width (W)	Acceptable Q'TY
Ignore	W≦0.03mm	Ignore
L≦8.0mm	0.03 <w≤0.05mm< td=""><td>6</td></w≤0.05mm<>	6
L≦5.0mm	0.05 <w≦0.1mm< td=""><td>4</td></w≦0.1mm<>	4
111	0.1mm <w< td=""><td>0</td></w<>	0

3.2.2 Touch Panel judgment specification as follow.

Length (L)	Width (W)	Acceptable Q'TY
Ignore	W≤0.03mm	Ignore
L≤12.0mm	0.03mm <w≤0.05mm< td=""><td>7</td></w≤0.05mm<>	7
L≤6.0mm	0.05mm <w≤0.1mm< td=""><td>5</td></w≤0.1mm<>	5
<u>5</u> ,	0.1mm <w< td=""><td>0</td></w<>	0

Note: Applicable to all sizes.

Judge as OK sample if defect is invisible in square viewing angle.

5"≦ LCD Size < 8" Size inspection criteria

3.3 Line type: (as following fig)

3.3.1 Applicable to LCM TFT, not including Touch Panel.



Length (L)	Width (W)	Acceptable Q'TY
Ignore	W≦0.03mm	Ignore
L≦8.0mm	0.03mm <w≦0.05mm< td=""><td>8</td></w≦0.05mm<>	8
L≦5.0mm	0.05mm <w≤0.1mm< td=""><td>6</td></w≤0.1mm<>	6
2	0.1mm <w< td=""><td>0</td></w<>	0

3.3.2 Touch Panel judgment specification as follow.

Length (L)	Width (W)	Acceptable Q'TY
Ignore	W≤0.03mm	Ignore
L≤12.0mm	0.03mm <w≤0.05mm< td=""><td>9</td></w≤0.05mm<>	9
L≦6.0mm	0.05mm <w≦0.1mm< td=""><td>7</td></w≦0.1mm<>	7
- 4	0.1mm <w< td=""><td>0</td></w<>	0

Note: Applicable to all sizes.

Ignore non-viewing area

Judge as OK sample if defect is invisible in square viewing angle.

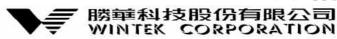




Wintek Display TFT Modul	NO. M1L070012 Inspection Criteria		
REVISION DATE: 2010/10/19	Version: V5.0	PAGE: 7 OF 10	

Γ			72			8"≤ LCD Size	Size inspection criteria		7	
			3.4 Line	type :	(as fo	ollowing fig)				
			3.4.1 Applicable to LCM TFT, not including Touch Panel.							
١			_	\ /	¥ W	Length (L)	Width (W)	Acceptable Q"	ГΥ	
			→	L	4	Ignore	W≤0.03mm	Ignore		
				1		L≦8.0mm	0.03mm <w≦0.05mm< td=""><td>8</td><td></td><td></td></w≦0.05mm<>	8		
١						L≦5.0mm	0.05mm <w≤0.1mm< td=""><td>6</td><td></td><td></td></w≤0.1mm<>	6		
		Naked line,					0.1mm <w< td=""><td>0</td><td></td><td></td></w<>	0		
	03	black&	25 10-2-20				12.5		4	Minor Defect
		white line	3.4.2 To	ouch Pa	anel ju	dgment specifica	ation as follow.			Delect
	4					Length (L)	Width (W)	Acceptable Q'	ΓY	
						Ignore	W≤0.03mm	Ignore		
						L≤12.0mm	0.03mm <w≤0.05mm< td=""><td>9</td><td></td><td></td></w≤0.05mm<>	9		
						L≦6.0mm	0.05mm <w≤0.1mm< td=""><td>7</td><td>ø.</td><td></td></w≤0.1mm<>	7	ø.	
l						==	0.1mm <w< td=""><td>0</td><td></td><td></td></w<>	0		
			IgnorJudg	re non- le as O	viewin K sam	ple if defect is in	visible in square viewing a		,	
			4.1 000	delect	(Alla		cable to TFT LCM, includi		,	
						Term	Size	Sub-pixel disabled		1
	04	Dot defect	or	or		Inspect in pixed	LCD Size < 3	3 (Note 1)	M	Minor
	4	201 001001	R	G	В	Inspect in pixed	2 ≥ FCD 2lZ6 ≥ 2	6 (Note 1)		Defect
						Inspect in pixed	5"< LCD Size	10 (Note 1)		
				allowe	ed.	ce of 2-separat	ed Sub-pixel failures w	ithin 5mm is	not	





Wintek Display TFT Module Inspection Criteria		NO. M1L070012 Inspection Criteria
REVISION DATE: 2010/10/19	Version: V5.0	PAGE: 8 OF 10

Polarizer O6 Scratches Follow No 03 Naked line, black& white line Symbols:			700001. 1000					
Polarizer O6 Scratches Follow No 03 Naked line, black& white line Symbols: x: Chip length y: Chip width z: Chip thickness k: Sealant width t: Glass thickness a: LCD length L: Electrode terminal length	05	Polarizer	Olf bubble and concave &convex dot are easily visible, judged by black spot Specification. Olf defect can only be found in particularly fixed angle, judged by this Specification. $ \phi = (x+y) / 2 $ Size Acceptable Q'TY $ \phi \le 0.20 \qquad \text{Ignore (accept no dense)} $ 0.20 < φ ≤ 0.50 3 0.50 < φ ≤ 1.00 2 1.00 < φ 0 Total QTY 3 O Judge as OK sample if defect is invisible in square viewing angle. Olf defect can be found in square fixed angle, judged by the rule above. Olgnore non-viewing area O Applicable to whole size. 5.2 Polarizer falling off glue must less than ≤ 0.5mm. Not over viewing area					
Symbols: x: Chip length y: Chip width z: Chip thickness k: Sealant width t: Glass thickness a: LCD length L: Electrode terminal length T: T/P thickness 7.1 General glass chip: 7.1.1 Chip on the panel surface and crack between panels: O7 Chipped glass TOUCH PANEL Mind Defe				Defec				
x: Chip length y: Chip width z: Chip thickness k: Sealant width t: Glass thickness a: LCD length L: Electrode terminal length T: T/P thickness 7.1 General glass chip: 7.1.1 Chip on the panel surface and crack between panels: Of Chipped glass TOUCH PANEL Minimal Chipped glass TOUCH PANEL TOUCH PANEL	06	Scratches	Follow No 03 Naked line, black& white line					
Bottom glass	07	Chipped glass	x: Chip length y: Chip width z: Chip thickness k: Sealant width t: Glass thickness a: LCD length L: Electrode terminal length T: T/P thickness 7.1 General glass chip: 7.1.1 Chip on the panel surface and crack between panels:	Minor Defect				





Wintek Display TFT Module	NO. M1L070012 Inspection Criteria	
REVISION DATE: 2010/10/19	Version: V5.0	PAGE: 9 OF 10

	1					
		a. General TFT pro	z : Chip thickness	y : Chip width		
		Top, bottom glass	z≦1/2t	y≦0.8	Ignore	
		Top, bottom glass	1/2t <z<t< td=""><td>y≤0.6</td><td>Ignore</td><td></td></z<t<>	y≤0.6	Ignore	
		Top glass	z = t	y≤0.5(Note 1)	Ignore	
		Bottom glass	z=t	y≤0.3(Note 1)	Ignore	
07	Chipped glass	○ Chip length s	hould not affect nage or destruct nent mark.		d be omitted. e circuit, conductible	e Minor Defect
4		x : length		width	z: thickness	
		x≤5.0mm		2.0mm	z≤T (Ignore)	
		circuit, conqu	ctible point and	and the second s	r destroy electrode	
	8.	1 Corner crack	ctible point and	and the second s	r destroy electrode	
1	8.		ctible point and	and the second s	r destroy electrode	
	8.	1 Corner crack	<u>L</u> y	alignment mark.		
	8.	1 Corner crack t X Z. a. General LCD TR	T product (T/P n	ot included, LCD	viewable)	
0.8	8. Corner	1 Corner crack	T product (T/P n	ot included, LCD		Minor
08		a. General LCD TF	FT product (T/P m ss y: Chi y≤ y≤1.0 (ot included, LCD o width 1.0 Note 2)	viewable) x : Chip length Ignore Ignore	Minor Defect





Wintek Display TFT Module	Inspection Criteria	NO. M1L070012 Inspection Criteria
REVISION DATE: 2010/10/19	Version: V5.0	PAGE: 10 OF 10

	x : length	y: width	z : thickness		
	x≤3.0mm	y≤3.0mm	z≤T		
O8 Corner crack	 For LCM+T/P s c. LCD has been pro Chip length sh Chip thickness 	or more chips, x is the tructure • judged by betected and not viewal ould not affect LCM as and width should not ble point and alignm	T/P specification. able assembly. ot damage or destro	D	Min-





Defect	Туре	Specification Size	Count(N)	Major	Minor
Dot Shape		D ≤0.25 mm	Ignored		
79	Scratch and Bubbles in	0.25mm < D ≤ 0.5mm	N ≤ 3		
display area		D > 0.5mm	N=0		•
Newton Ring (Only for Touch panel)		D≤70mm	N≤4		*
		D>70mm	N=0		•
TOD 5: 1 5	(0.1.6. T. 1. IV	0.1mm <d≤0.2mm< td=""><td>N≤4</td><td></td><td></td></d≤0.2mm<>	N≤4		
TSP FISH E	yes (Only for Touch panel)	0.2mm <d≤0.3mm< td=""><td>N≤3</td><td></td><td>•</td></d≤0.3mm<>	N≤3		•
(Bubble/De	nt)	0.3mm <d≤0.4mm< td=""><td>N≤2</td><td></td><td></td></d≤0.4mm<>	N≤2		
Line Shap		W ≤ 0.01 mm	Ignored		87
(17)	Scratch · Lint and Bubbles	$0.01 mm < W \leq 0.05 mm$ and L $\leq 3 mm$	N ≤ 3		•
-	-L	W > 0.05mm or L > 3 mm	N=0		
Bubble in cell (active area)		It should be found by eyes			•
	Scratch	No harm No harm			. •
Bezel	Dirt				•
	Wrap			3	1.
	Sunken			28	: •
	No label			•	
	Inverted label	No			•
	Broken		5.8	•	
Labat	Dirt	Word can be read.		•	
Label	Not clear	No No			•
	Word out of shape				•
	Mistake				
	Position	Be attached on right position			•
Screw	Not enough	No			•
Sciew	Limp	No			•
Connector	Connection status	No bend on pins and dama			
FPC/FFC	Broken	No		•	



5.2 Standard Specification for Reliability



產品名稱:顯示器/觸控 模組 Product Name: Display/TP

Module

模組信賴性規格

Product Reliability Test Standard

頁次 Page: 1/3

規範編號 No: M3ET090001

適用範圍

含電容式觸控面板中小尺寸顯示器模組

Medium/Small Size Display Module with Capacitive Touch Panel Applied Scope

版本	修改者	版次履歷	日期
Version	Reviser	History	Date
V1.0	陳世正	New Version 新版本	2009,01,06
V2.0	陳世正	 To modify High temperature resistance Description. To delete the statement" and allowing it stand for 30 minutes." (安设耐高溫性描述 刪除 allow it stand for 30 minutes 的描述 To modify Low temperature resistance Description.	2009,02,23
V3.0	陳世正	 To modify cycle times of Thermal shock resistance from 20 to 30 times (家政耐熱衝擊性循環次數由 20 次改為 30 次 To modify Product Name and Applied Scope (家政產品名稱及適用範圍 	2010,11,19

2009/1/06 發行	核准 Approval	審查 Survey	擬案 Proposal
Issued: 2009/1/06			
2010/11/29 第 2 次修訂	王文宏	林志強	陳世正
Revision : the 2 Edition			





產品名稱: 顯示器/觸控 模組 Product Name: Display/TP

Name: Display/TP Module

模組信賴性規格

Product Reliability Test Standard

頁次 Page: 2/3 規範編號 No: M3ET090001

適用範圍

含電容式觸控面板中小尺寸顯示器模組

Applied Scope

Medium/Small Size Display Module with Capacitive Touch Panel

1. Standard Specifications for Reliability of LCD Module

液晶顯示器模組信賴性規格

NO	Test Item	測試條件 / Description of Test Condition
01	High temperature Operation 高溫操作	Operating temperature (high) of the sample should be allowed to stand for 240 hours under driving condition. 在高溫動態條件下放置 240 小時
02	Low temperature Operation 低溫操作	Operating temperature (low) of the sample should be allowed to stand for 240 hours under driving condition. 在低溫動態條件下放置 240 小時
03	High temperature resistance 耐高溫性	Storage temperature (high) of the sample should be allowed to stand for 240 hours under no-load condition, and then returning it to normal temperature condition. 在高溫靜態條件下放置 240 小時,然後將它放回室溫條件
04	Low temperature resistance 耐低溫性	Storage temperature (low) of the sample should be allowed to stand for 240 hours under no-load condition, then returning it to normal temperature condition. 在低溫靜態條件下放置 240 小時,然後將它放回室溫條件
05	Moisture resistance 耐濕性	The sample should be allowed to stand at 60 ℃, 90% RH MAX for 240 hours under no-load condition excluding the polarizer, then taking it out and drying it at normal temperature. 在 60 ℃最大濕度 90% RH 的靜態條件下放置 240 小時,然後將它放回室溫條件下晾乾
06	Thermal shock resistance 耐熱衝擊性	The sample should be allowed to stand the following 30 cycles of storage: Storage temperature (low) for 30 minutes → normal temperature (high) for 30 minutes → normal temperature for 5 minutes , as one cycle. 產品在以下環境中循環 30 次: 低溫條件中 30 分鐘 室溫下 5 分鐘 高溫條件下 30 分鐘 室溫下 5 分鐘

Notes: Please refer to section 1.1 Absolute Maximum Ratings to mention the operating temperature and storage temperature.

注意:請參考 section 1.1 操作溫度與存儲溫度的等級





產品名稱:顯示器/觸控 模組 Product Name: Display/TP

Module

模組信賴性規格

Product Reliability Test Standard

頁次 Page: 3/3 規範編號 No: M3ET090001

適用範圍

含電容式觸控面板中小尺寸顯示器模組

Applied Scope

Medium/Small Size Display Module with Capacitive Touch Panel

2. Testing Conditions and Inspection Criteria

測試條件&檢驗規範

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 4.2-1, Standard specifications for Reliability have been executed in order to ensure stability.

在 4.2-1 表中的信賴性試驗完成後,模組必須在室溫環境下放置 24 小時再進行最終檢驗,以保證測試結果的可靠性。

NO	Item	Test Model	Inspection Criteria
01	Current Consumption 耗電流	然者 理	The current consumption should conform to the product specification. 耗電流應符合產品規格表
02	Contrast 對比度	Refer To Specification 參考規格表	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests. 經過測試後的對比度必須大於測試前的一半
03	Appearance 視效	Visual inspection 目測	Defect free. 無缺陷

3. Life Time

Life time 壽命 Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm10^{\circ}$ C), normal humidity ($45\pm20^{\circ}$ RH), and in area not exposed to direct sun light. (Life time of backlight, please refer to "Data about backlight".)

在室溫(25 ±10℃),正常濕度(45 ±20% RH)無直接日光照射條件下正常操作或存儲,在 50000 小時内功能,特性,視效等應該無明顯衰退(背光壽命請參考" Data about backlight")

Note: From our experience the life time of high humidity operation and high temperature operation as above mentioned could be achieved.

注意:根據我們的經驗,高溫高濕操作可能會超出以上提到的。



5.3 Precautions in Use of LCM

5.3-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.

5.3-2 Storage

- Store in an ambient temperature of 25 ± 5 , and in a relative humidity of 40% to 60%. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

5.3-3 Soldering

- Use the Sn-Ag-Cu (96.5, 3.0, 0.5) solder
- Iron: Temperature 300 and less than 5-6 sec during soldering.
- Rewiring : no more than 3 times.

5.3-4 Assembly

The front polarizer is covered with a protective foil which should be removed before use.



(6) Substance Management Units

6.1 Product Substances Management Documentation

RoHS Directive Requirements	No	C21-4	4	
ROHS Directive Requirements	VER	4	Page	1/20

Version	Description	Date	Creator	Approver
1	本檢驗規格依據環資"客戶產品環保規範"	30-Nov-2005	盧承劭	陳志明
2	依據客戶"Quanta Material Restricted for Use", 2008.09.01 文件進行修訂	3-Sep-2008	王永豪	吳學智
3	依據客戶"Quanta Material Restricted for Use", 2010.02.24 文件進行修訂	2010/07/20	連志賢	尤鵬智
4	依據客戶"Quanta Material Restricted for Use", 2011.05.01 文件進行修訂	2011/6/30	鐘凱彥	王國欣



DaUS Directive Dequirements	No	С	21-4	
RoHS Directive Requirements	VER	4	Page	2/20

A. Prohibited Substances List (禁用物質表)

Item 項目	Material 管制物質	Controlled Applications	Unit	Compliance Level 環保等級		
須日	官 帕物負	管制範圍	平1世	EP	EU	EUL
1	2,4,6-Tri-t-Butylphenol 三異丁基苯	All applications 所有範圍均適用	ppm	N.D	-	
2	4-Nitrobiphenyl and its salt 4-硝基聯和它的鹽	All applications 所有範圍均適用	ppm	N.D	-	Î
3	Aldrin 艾氏劑	All applications 所有範圍均適用	ppm	N.D	-	1
4	Alkylphenols 烷基苯酚	All applications 所有範圍均適用	ppm	1000	=	, <u> </u>
5	Asbestos and its Compounds 百棉和它的化合物	All applications 所有範圍均適用	ppm	N.D	_	(1 <u>114</u>)
6	Azocolurants and azodyes which form certain aromatic amines 偶氮染料和颜料構成某些芳香胺	(1) In textile and leather articles which may come into direct and prolonged contact with human skin. 紡織和皮革品 (2) In colorants for textile and leather articles. 有著色紡織和皮革品		(1)30 (2)1000		
7	Benzene 苯	All applications 所有範圍均適用	ppm	(1)5 (Free status) (2)1000 (article)	-	s - -



RoHS Directive Requirements	No	C	21-4	
Rons Directive Requirements	VER	4	Page	3/20

8	Bis(choromenthyl)ether 雙醚	All applications 所有範圍均適用	ppm	N.D		<u>- 1</u>
9	Chlordanes 氣丹	All applications 所有範圍均適用	ppm	N.D	_	ŧ
10	Chlorinated Hydrocarbons 氧化碳氫化合物	(1)All applications 所有範圍均適用 (3) In cleaning agents and adhesives. 清潔劑和膠黏劑	ppm	(1)1000 (2)N.D		(1
11	Coal Tar Distillates, heavy oils 煤焦油餾分油。重油	All applications 所有範圍均適用	ppm	1000	S = .	- 1
12	Coal Tar Distillates, heavy oils,pyrene fraction 煤焦油餾分油、重油、莊分數	All applications 所有範圍均適用	ppm	1000	=	· ·
13	Coal Tar Distillates, heavy oils, pyrene fraction 煤焦油餾分油,重油,莊分數	Wood 木材	ppm	N.D	-	
14	Coal Tar Residues, pitch distn 煤焦油殘渣、瀝青輕油	All applications 所有範圍均適用	ppm	1000	=	_
15	Creosote, coal tar, tar oils, anthracene substances 木鰡油,煤焦油,焦油,蒽物質	Prohibited for the treatment of wood 禁止爲治療木材	ppm	N.D	-	Ī
16	Cyclohexane 環己烷	Adhesive 膠粘劑	ppm	1000	_	-
17	DDT 二氯二苯三氯乙烷	All applications 所有範圍均適用	ppm	N.D	-	-
18	Dibutyltin (DBT) compounds 二丁基錫化合物	All applications 所有範圍均適用	ppm	1000	-	_
19	Dieldrin 殺蟲劑	All applications 所有範圍均適用	ppm	N.D	-	-



RoHS Directive Requirements	No		C21-4	
	VER	4	Page	4/20

20	Dimethyformamide (DMF) 二甲基甲醯胺	All applications 所有範圍均適用	ppm	0.1	-	-
21	Dioctyltin (DOT) compounds 二辛基錫化合物	Textile and leather	ppm	1000	-	_
22	Dioxins 戴奥辛	All applications 所有範圍均適用	ppm	N.D	-	-
23	Diphenylether, octabromo derivative (C12H2Br8O) 二苯醚・八溴衍生物	All applications 所有範圍均適用	ppm	1000	-	N.
24	Di-u-oxo-di-n-butylstanniohydrox Yborane (DBB) 二-m-氧-二-n-丁基-錫羥基 xy 硼烷	In preparations 準備	ppm	1000	-	
25	Endrin 殺蟲藥	All applications 所有範圍均適用	ppm	N.D	-	= 3
26	Expanded polystyrene (EPS) 聚苯乙烯	Packaging to South Korea 包裝給南韓	ppm	N.D	_	
27	Fluorinated Greenhouse Gases 氟化溫室氣體	All applications 所有範圍均適用	ppm	N.D	-	
28	Formaldehyde 甲醛	(1) Wooden material in electronic and mechanical components of final product. 木製材料在電子和機械的完成品零件 (2) Textile 紡織品	ppm	(1) N.D (2) 75		
29	Halogenated Diphenyl Methanes 鹵代甲烷二苯基	All applications 所有範圍均適用	ppm	N.D	-	- 3



RoHS Directive Requirements	No C21-4			
	VER	4	Page	5/20

30	Hexachlorobenzene 六氯苯	All applications 所有範圍均適用	ppm	N.D	-	-
31	Hexachlorobutadiene 六氯丁二烯	All applications 所有範圍均適用	ppm	N.D	-	e -
32	Hexachlorobenzene isomers(HCH) 六氯苯異構體	All applications 所有範圍均適用	ppm	N.D	=	-
33	Kelthane 三 氣殺醇	All applications 所有範圍均適用	ppm	N.D.	=	
34	Lead carbonates 鉛碳酸鹽	Paint 塗料	ppm	100		Į.
35	Lead sulphates 鉛硫酸鹽	Paint 塗料	ppm	100	-	-
36	Methyl chloroform 甲基氯仿	All applications 所有範圍均適用	ppm	N.D	_	J
37	Mirex 滅蟻囊	All applications 所有範圍均適用	ppm	N.D		<u> </u>
38	Monomethyl-dibromo-diphenylmethane bromobenzylbromotoluene, mixture of isomers(DBBT) 单甲基二溴二苯基甲烷	All applications 所有範圍均適用	ppm	1000		
39	N,N'-ditolyl-p-phenylenediamin, N-tolyl-N'-xyly I-p-phenylenediamine or N, N'-dixylyl-p-phenylene diamine 二甲苯基对苯二胺	All applications 所有範圍均適用	ppm	N.D		: -
40	Nickel and its Compounds 鎮和它的化合物	Components that intended to come into direct and prolonged contact with the skin 會跟皮膚長期接 觸的物質	ppm	0.5ug/cm2/week	=	



Dalië Dianatian Daminananta	No		C21-4	
RoHS Directive Requirements	VER	4	Page	6/20

41	Nonylphenol/ethoxylates (NP/NPEs) and related substances 壬基酚/聚氧乙烯醚和 有關物質	All applications 所有範圍均適用	ppm	1000	_	-
42	Organic Tin compounds 有機的錫化合物	All applications 所有範圍均適用	ppm	N.D	=	
43	Ozone Depleting Substances 消耗臭氧層物質	All applications 所有範圍均適用	ppm	N.D	-	7
44	Pentachlorophenol(PCP) and its salts and esters 五氯苯酚及其鹽類和酯類	All applications 所有範圍均適用	ppm	1000	<u> </u>	9
45	Perfluorooctane sulfonates (PFOS) 全氟辛烷磺酸鹽	(1)All application, exception is applicable to PFOS directive 所有範圍均適用 例外於 PFOS 指令 (2)In preparations, exception is applicable to PFOS directive 在準備工作均適用例外於 PFOS 指令 (3)Textile, Leather and coating 約織,皮革,塗	ppm	(1)1000 (2)50 (3)1 (4)-		



DaUS Directive Dequirements	No	C	21-4	
RoHS Directive Requirements	VER	4	Page	7/20

		100	190	160	90	
		料 (4)PFOS using in part is application for exemption of PFOS directive PFOS 使用部分 申請豁免 PFOS 指令				
46	Polychlorinated Biphenyls (PCBs) and specific substitutes 多氨聯苯和具體的替代品	All applications 所有範圍均適用	ppm	N.D		-
47	Polychlorinated dibenzodioxins (PCDDs) 多氧二苯	All applications 所有範圍均適用	ppm	N.D	-	=
48	Polychlorinated dibenzofurans (PCDDs) 多氨二苯並呋喃	All applications 所有範圍均適用	ppm	N.D	_	=
49	Polychlorinated Naphthalenes (PCNs) 多氧化萘	All applications 所有範圍均適用	ppm	N.D	=	=
50	Polychlorinated Terphenyls (PCTs) 多氧三聯苯	All applications 所有範圍均適用	ppm	N.D		-
51	Polycyclic aromatic hydrocarbons (PAHs) 多環芳香煙	(1)Long-term skin contact: External cases for portable device, Desktop keyboard and mouse, Protable computer input devices, External Power Suppliers, Cables	ppm	(1)Benzo[a]pyren:1 Sum 16 PAH (EPA):10 (2)Benzo[a]pyren:20 Sum 16 PAH(EPA):200		==



RoHS Directive Requirements	No		C21-4	
Kons Directive Requirements	VER	4	Page	8/20

100		130 001
	長期皮膚接觸:	
	外部案件的便攜	
	設備,台式機的	
	鍵盤和鼠標・便	
	攜式計算機的輸	
	入設備・外部電	
	源供應器,電纜	
	(2)Short-term	
	skin contact or	
	without skin	
	contact: External	
	cases for	
	stationary	
	devices,	
	Desktop PCs,	
	Monitors,	
	External Power	
	Suppliers,	
	Power Cables	
	短期皮膚接觸或	
	不接觸皮膚:外	
	部案件的固定裝	
	置,桌上型電	
	脳・順示器・外	
	部電源供應器・	
	電源線	
	(3)Testing and	
	Validation of	
	Polycyclic	
	Aromatic	
	Hydrocarbons	
	(PAH) in the	
	course of	



Dalic Directive Dequirements	No		C21-4	
RoHS Directive Requirements	VER	4	Page	9/20

	8		22 22		22 3	3,70
		GS-Mark Certification,				
		Zek 01-08 測試和驗證的多				
		環芳煙(PAH) 在使用過程中的				
		GS - Mark 認 證・ZEK 01-08				
52	Radioactive Substances (Radioactive Isotope) 放射性物質	All applications 所有範圍均適用	ppm	N.D		=
53	Specific benzotriazole 特定苯並三氮唑	All applications 所有範圍均適用	ppm	N.D	-	450
54	Toluene 甲苯	In adhesives and spray paints	ppm	1000	-	-
55	Toxaphene 毒殺芬	All applications 所有範圍均適用	ppm	N.D	-	=
56	Tri-(1-aziiridinyl) 三(1-氮丙啶基)	textile articles 紡織製品	ppm	N.D	_	_
57	Tri-(2,3-dibromo-propyl) Phosphate 三 (2,3-二溴丙基)磷酸酯	textile articles 紡織製品	ppm	N.D	-	-
58	Tri-substituted organostannic Compounds 三取代有機錫化合物	All applications 所有範圍均適用	ppm	1000	-	=
59	Yellow Phosphorus 黃磷	All applications 所有範圍均適用	ppm	N.D	-	=



RoHS Directive Requirements	No		C21-4	
Rons Directive Requirements	VER	4	Page	10/20

B. Halogen-Free (HF) Requirements

無鹵素(Halogen Free)要求規範

Item 項目			Unit	Compliance Level 環保等級				
供日	百利物員	各种种组制	單位	EP	EU	EUL		
1	Bromine (Br) 溴	All applications 所有範圍均適用	ppm	900	-			
2	Chlorine (CI) 氨	All applications 所有範圍均適用	ppm	900	17	-		
3	Total Br+Cl 總溴和總氯	All applications 所有範圍均適用	ppm	1500	-	-		
備註	The state of the s	cted (< MDL 低於最低偵測極限) compliance level 環保等級定義如下	圖		,			





RoHS Directive Requirements	No	С	21-4	W	3
Kons Directive Requirements	VER	4	Page	11/20	

溴和氯物質(Bromine and Chlorine Substance)要求規範

		Controlled Applications	Unit	Compliance Level 環保等級		
項目	官制初頁	管制範圍	里11	EP	EU	EUL
1	Brominated Flame Retardants (BFRs) 溴	All applications with no exceptions 所有範圍均適用沒有例外	ppm	900	-	= -
2	Chlorinated Flame Retardants (CFRs)	All applications with no exceptions 所有範圍均適用沒有例外	ppm	900	15	1.5
3	Polyvinyl chloride (PVC) 聚氯乙烯	All applications with no exceptions 所有範圍均適用沒有例外	ppm	Negative	10	- (2
4	Tertabromobisphenol A, TBBPA 四溴双酚 A	All applications 所有範圍均適用	Ppm	900		
5	Hexabromocyclododecane (HBCCD) 六溴环十二烷	All applications 所有範圍均適用	Ppm	900		
6	Short-chain Chlorinated Paraffins (C10-C13) 短鍊氯化石蠟	All applications 所有範圍均適用	Ppm	900		
7	Medium-chained chlorinated paraffins C14-C17 (MCCP) 中鏈氯化石臘	All applications 所有範圍均適用	ppm	900		



D-HCD:tiDtt-	No	No C21-4			
RoHS Directive Requirements	VER	4	Page	12/20	

C. Substances for reporting (物質的報告)

Item 項目	Material 管制物質	Controlled Applications	Unit 單位	Compl環保等	iance L 級	evel
項目	自即物具	日中5年8日	平世	EP	EU	EUL
1	Antimony its compounds 銷及其化合物	All applications 所有範圍	ppm		_	1
2	Antimony Trioxide (Sb2O3) 三氧化二餅	All applications 所有範圍	ppm	<u>=</u>	=	-
3	Arsenic and its compounds	All applications 所有範圍	ppm	4F)	. .	
4	Beryllium and its compounds 鈹及其化合物	All applications 所有範圍	ppm	=	-	-
5	Bismuth and its compounds 鮅及其化合物	All applications 所有範圍	ppm	=	_	_
6	Bisphenol A 雙酚 A	All applications 所有範圍	ppm	=	-	
7	Brominated Flame Retardants 溴化阻燃劑	All applications 所有範圍	ppm	-	-	Ē
8	Chlorinated Flame Retardants (CFRs) 氯化阻燃劑	All applications 所有範圍	ppm	: -	9 7.5 2	-
9	DHTDMAC, DODMAC/DSDMAC, DTDMAC (surfactants and its compounds) 表面活性劑及其化合物	All applications 所有範圍	ppm	-	-	
10	Expanded polystyrene (EPS) 發泡聚苯乙烯	All packaging Materials 所有包裝材料	ppm	:== :		Ĭ.
11	Hexabromocyclododecane (HBCCD) 大溴	All applications 所有範圍	ppm	100	822	-
12	Medium-chained chlorinated	All applications	ppm	1000	-	-



RoHS Directive Requirements	No C21-4				
Kons Directive Requirements	VER	4	Page	13/20	

	paraffins C14-17(MCCP) 中鏈氧化石蠟	所有範圍				
13	Musk ketone 麝香酮	All applications 所有範圍	ppm	850	177	· - -
14	Nickel and its Compounds 鎮及其化合物	All applications 所有範圍	ppm	× 51	-	
15	Phthalates(other than DEHP, DBP, BBP, DINP, DIDP, DnOP, DnHP, DIBP) 磷苯二甲酸鹽類	All applications 所有範圍	ppm	ŧ.	-	Ī
16	Bis(2-ethylhexyl) phthalate(DEHP) 鄰苯二甲酸二 (2-乙基己基) 酯	All applications 所有範圍	ppm	8 4	-	3
17	Dibutyl Phthalate (DBP) 鄰苯二甲酸二丁酯	All applications 所有範圍	ppm	8 4		-
18	Benzyl butyl phthalate (BBP) 苯二甲酸苄丁酯	All applications 所有範圍	ppm	R <u>84</u>	423	
19	Diisononyl phthalate (DINP) 二異壬酯	All applications 所有範圍	ppm	-	-	-
20	Diisodecyl phthalate (DIDP) 二異奏酯	All applications 所有範圍	ppm	13 <u>24</u>	4 <u>2</u> 3	_
21	Di-n-octyl phthalate (DOnP) 鄰苯二甲酸二丁酯	All applications 所有範圍	ppm	1 5	-	-
22	Di-n-hexyl phthalate (DnHP) 苯二甲酸二己酯	All applications 所有範圍	ppm	9 <u>24</u>	<u> 1900</u> 3	
23	Diisobutyl phthalate (DIBP) 鄰苯二甲酸二異丁酯	All applications 所有範圍	ppm	S ol	, 1	-
24	Perchlorate Compounds 高氯酸鹽	Batteries and Battery Packs 電池及電池包裝	ppm	<u>824</u>	<u> </u>	<u>12.</u>
25	Perfluorooctyl acid (PFOA) and individual salts and	All applications 所有範圍	ppm	61 8-1		-



Dalič Directive Dequirements	No C21-4				
RoHS Directive Requirements	VER	4	Page	14/20	

	esters of PFOA 全氟辛酸					
26	Phosphorus (P)and its compounds	All applications 所有範圍	ppm	<u> </u>		1 <u>22</u> ;
27	Polyvinyl chloride (PVC) 聚氯乙烯	All applications 所有範圍	ppm	827		-
28	Selenium and its compounds 硒及其化合物	All applications 所有範圍	ppm	₹ #	-	-
29	Short-chain Chlorinated Paraffins (C10-C13) 短鏈氯化石蠟	All applications 所有範圍	ppm	R <u>86</u>	= <u></u>	_
30	Tetrabromobisphenol A, TBBPA 四溴雙酚 A	All applications 所有範圍	ppm	1 -	-	1=1
31	Triclosan 三氣沙	All applications 所有範圍	ppm	6 <u>24</u>	<u>**</u>	12

G. REACH Requirements (REACH 要求規範)

跟據最新的 Substances of Very High Concern (SVHC)列表,請依循 REACH 網站和 Green Quant 網站

(1) REACH 網站:

http://ec.europa.eu/environment/chemicals/reach/reach_intro.htm

http://echa.europa.eu/chem_data/authorisation_process/candidate_list_table_en.asp

(2) Green Quanta 網站:

http://green.quantatw.com/index.htm





Paus Directive Paguirements	No C21-4				
RoHS Directive Requirements	VER	4	Page	15/20	

EU RoHS Exemptions(歐盟排外條款)

Items	Exemption Clauses					
1	Mercury in compact fluorescent lamps not exceeding 5 mg per lamp 小型日光燈中的汞含量不得超過 5 毫克/燈					
2	Mercury in straight fluorescent lamps for general purposes not exceeding: - halophosphate 10 mg - triphosphate with normal lifetime 5 mg - triphosphate with long lifetime 8 mg 般用途的直管日光燈中的汞含量不得超過: - 含鹵素磷酸鹽 10 毫克 - 三磷酸鹽 5 毫克 - 長效三磷酸鹽 8 毫克					
3	Mercury in straight fluorescent lamps for special purposes. 特殊用途的直管日光燈中的汞含量					
4	Mercury in other lamps not specifically mentioned in annex of 2002/95/EC. 2002/95/EC 附件中未特別提及的其它照明燈中的汞含量					
5	Lead in glass of cathode ray tubes, electronic components and fluorescent tubes. 陰極射線管、電子零件和發光管的玻璃內的鉛含量					
6	Lead as an alloying element in steel containing up to 0.35% lead by weight, aluminium containing up to 0.4% lead by weight and as a copper alloy containing up to 4% lead by weight. 劉中合金元素中的鉛含量達 0.35%、鉛含量達 0.4%、銅合金中的鉛含量達 4%					
7	- lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) - lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for Telecommunications - Lead in electronic ceramic parts (e.g.piezoelectronic devices) - 高熔點銲錫中的鉛(如:鉛含量 ≥85% 的合金中的鉛); - 用於伺服器・記憶體和存儲陣列系統的焊料中的鉛。用於交換、信號產生和傳輸,以及電信網路管理的網路基礎設施設備焊料中的鉛。 - 電子陶瓷零件中的鉛 (e.g.piezoelectronic devices)					



RoHS Directive Requirements	No	No C21-4			
	VER	4	Page	16/20	

8	Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (1) amending Directive 76/769/EEC (2) relating to restrictions on the marketing and use of certain dangerous substances and preparations 電接點中的鍋及鍋化合物以及 91/338/EEC 指令限制範圍以外的鍋電銀層中的鍋
9	Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators. 在電冰箱中作馬碳鋼冷藏系統防腐劑的六價鉻
10	Lead used in compliant pin connector systems 順應針連接系統中使用的鉛
11	Lead as a coating material for the thermal conduction module c-ring 熱導槍釘模組塗層中所用的鉛
12	Lead and cadmium in optical and filter glass 光學玻璃及濾光玻璃中所用的鉛及鍋
13	Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight 微處理器針腳及封裝連接所使用的含兩種以上組成焊料中的鉛(鉛含量在80%-85%之間)
14	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages 用於焊接半導體終端和集成電路板載體焊料中的鉛
15	DecaBDE in polymeric applications 聚合體中使用的十溴聯苯醚
16	Lead in lead-bronze bearing shells and bulbs 在鉛-銅軸承外殼的鉛
17	Lead in linear incandescent lamps with silicate coated tubes 管狀白熾燈矽酸鹽塗層燈管中的鉛
18	Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications 用於專業複印設備之高強度放電燈 (HID) 中的鹵化鉛發光劑



D-HCD:ti Dtit-	No	C	21-4	
RoHS Directive Requirements	VER	4	Page	17/20

19	Lead as activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb) as well as when used as specially lamps for diazo-printing reprography, lithography,insect traps,photochemical and curing processes containing phosphors such as SMS ((Sr,Ba)2MgSi2O7:Pb). 仿日曬含磷(例如:BSP)放電燈中螢光粉的鉛活化劑(鉛含量 1%以下),以及二氮化合物印刷,平版印刷複印,捕蟲器,光化學及硬化製程使用的含磷(例如:SMS)放電燈中螢光粉的鉛活化劑
20	Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL) 小型省能燈泡中含 PbBiSn-Hg 及 PbInSn-Hg 成分之主要汞合金中的鉛以及含 PbSn- 之輔助汞合金中的鉛
21	Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD) 液晶顯示器中連接前後平版螢光燈基質的玻璃中的氧化鉛
22	Lead and cadmium in printing inks for the application of enamels on borosilicate glass. 用於硼砂玻璃瓷漆的印墨中的鉛及鍋
23	Lead as impurity in RIG (rare earth iron gamet) Faraday rotators used for fibre optic communication systems. 用於光纖通訊系統,以稀土鐵石榴石晶體製成的法拉第旋轉器中作爲雜質的鉛
24	Lead in finishes of fine pitch components other than connectors with a pitch of 0.65mm or less with NiFe lead frames and lead in finishes of fine pitch components other than connectors with a pitch of 0.65mm or less with coppler lead frames. 小螺距零件表面材料所含的鉛
25	Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors. 通孔盤狀及平面陣列陶瓷多層電容器焊料所含的鉛



RoHS Directive Requirements	No	C21-4		
	VER	4	Page	18/20

26	Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements, notably in the front and rare glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit and fritring as well as in print pastes 電漿顯示器及表面傳導式電子發射顯示器的構件所用的氧化鉛			
27	Lead oxide in the glass envelope of Black Light Blue (BLB) lamps. 藍黑燈管 (BLB) 玻璃外罩所含的氧化鉛			
28	Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125 dB SPL and above) loudspeakers. 在大功率揚聲器中作爲轉換器焊料的鉛合金 (2006/691/EC)			
29	Lead bound in crystal glass as defined in Annex I (Category 1,2,3 and 4) of Council Directive 69/493/EEC 在第 69/493/EEC 號指令附件 1 第 1 · 2 · 3 及 4 分類定義下之水晶玻璃鉛			
30	Cadmium alloys as electrical/mechanical solder joints to electrical conductors located directly on the voice coil in transducers used in high-powered loudspeakers with sound pressure level of 100 dB (A) and more. 音壓大於 100dB(A) 的大功率揚聲器中,與音圈轉換器連接電導體之電機/機材與料中的鍋合金			
31	Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting). 無汞平板螢光燈 (例如用於液晶螢幕、設計或工業照明) 中的銲料所含的鉛			
32	Lead oxide in seal frit used for making window assemblies for Argon and Krypton laser tubes.			
33	Lead in solders for the soldering of thin copper wires of 100um diameter and less in power transformers. 鉛焊料的焊接細銅線直徑寫 100um 的少的電力變壓器			
34	Lead in cermet-based trimmer potentiometer elements. 金屬陶瓷中的鉛的微調電位器元件			



DaUC Directive Dequirements	No	C	C21-4			
RoHS Directive Requirements	VER	4	Page	19/20		

35	Lead in the plating layer of high voltage diodes on the basis of a zinc borate glass body. 鉛電雙層的高電壓二極管的基礎上的硼酸鋅玻璃體內
36	Cadmium and cadmium oxide in thick film pastes used on aluminum bonded beryllium oxide. 编和氧化鍋的厚膜漿料用於鋁結合氧化鈹
37	Cadmium in color converting II-VI LEDs (<10ug Cd per mm2 of light-emitting area) for use in solid stats illumination or display systems 鍋在色彩轉換 II - VI 發光二極管(<10ug 鍋每平方毫米的發光區)統計使用固體照明或顯示系統

Note: The exemption list is being reviewed and subject to adjustment in the coming months.





DaUC Directive Dequirements	No	C	C21-4		
RoHS Directive Requirements	VER	4	Page	20/20	

Exemptions in 2006/122/EC (PFOS Directive)

tem	Exemption Clauses
1	Photoresists or anti reflective coatings for photolithography processes 照相平版印刷程序的光阻或抗反射塗層
2	Photographic ocatings applied to films, papers, or printing plates, 用於膠捲、相紙或印版的照相塗層
3	Mist suppressants for non-decorative hard chromium (VI) plating and wetting agents for use in controlled electronplating systems where the amount of PFOS released into the environment is minimised, by fully applying relevant best available techniques developed within the framework of Council Directive 96/61/EC of 24 September 1996 concerning intergrated pollution prevention and control 非裝飾性六價鉻鍍層的抗霧劑,或受控制的電鍍系統的潤濕劑,其中 PFOS 排放到環境中的量採用在理事會 1996 年 9 月 24 日發佈的 96/61/EC 指令"關於整合污染防治和控制"的機礎上形成的相關的最佳技術來降到最低
4	Hydraulic fluids for aviation 液壓機液體

